

Title (en)  
IMPACT RESISTANT THERMOPLASTIC MOLDING MATERIALS COMPRISED OF SYNDIOTACTIC POLYSTYRENE, GLASS FIBERS AND THERMOPLASTIC ELASTOMER (TPE) IMPACT MODIFIERS

Title (de)  
SCHLAGZÄHE THERMOPLASTISCHE FORMMASSEN AUS SYNDIOTAKTISCHEM POLYSTYROL, GLASFASERN UND TPE-SCHLAGZÄHMODIFIER

Title (fr)  
MATIERES DE MOULAGE THERMOPLASTIQUES RESILIENTES A BASE DE POLYSTYRENE SYNDIOTACTIQUE, DE FIBRES DE VERRE ET DE MODIFICATEURS DE RESILIENCE TPE

Publication  
**EP 1280855 A1 20030205 (DE)**

Application  
**EP 01933768 A 20010328**

Priority  
• DE 10016262 A 20000403  
• EP 0103504 W 20010328

Abstract (en)  
[origin: WO0174942A1] The invention relates to thermoplastic molding materials containing, as essential constituents: A) 5 to 96 wt. % of a vinyl aromatic polymer having a syndiotactic structure; B) 2 to 50 wt. % of an inorganic filler; C) 1 to 15 wt. % of a thermoplastic elastomer based on copolymers comprised of vinyl aromatic monomers, dienes and, optionally, 1,1-diphenylethylene; D) 1 to 10 wt. % of a compatibility mediator, optionally; E) 1 to 15 wt. % of a rubber-elastic particle-shaped styrene/diene block copolymer whose portion of diene can be completely or partially hydrogenated, and optionally; F) additives, whereby the weight percentages from A) to F) total 100.

IPC 1-7  
**C08L 25/06**; **C08K 3/00**; **C08K 7/14**

IPC 8 full level  
**C08J 5/00** (2006.01); **C08K 7/14** (2006.01); **C08L 25/00** (2006.01); **C08L 25/06** (2006.01); **C08L 53/02** (2006.01); **C08L 51/08** (2006.01); **C08L 71/12** (2006.01)

CPC (source: EP US)  
**C08L 25/06** (2013.01 - EP US); **C08L 51/08** (2013.01 - EP US); **C08L 53/02** (2013.01 - EP US); **C08L 71/12** (2013.01 - EP US)

Citation (search report)  
See references of WO 0174942A1

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**WO 0174942 A1 20011011**; AU 6016501 A 20011015; DE 10016262 A1 20011004; EP 1280855 A1 20030205; JP 2003529655 A 20031007; US 2003134964 A1 20030717; US 6762218 B2 20040713

DOCDB simple family (application)  
**EP 0103504 W 20010328**; AU 6016501 A 20010328; DE 10016262 A 20000403; EP 01933768 A 20010328; JP 2001572623 A 20010328; US 24068102 A 20021003